

# TEMIC

Siliconix

# VN0808L/M, VQ1006P

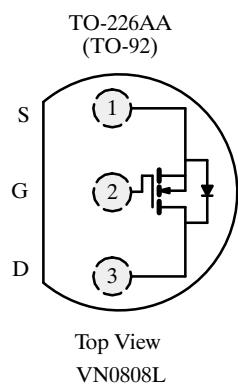
## N-Channel Enhancement-Mode MOS Transistors

### Product Summary

Part Number	$V_{(BR)DSS}$ Min (V)	$r_{DS(on)}$ Max ( $\Omega$ )	$V_{GS(th)}$ (V)	$I_D$ (A)
VN0808L	80	4 @ $V_{GS} = 10$ V	0.8 to 2	0.3
VN0808M			0.8 to 2	0.33
VQ1006P	90	4 @ $V_{GS} = 10$ V	0.8 to 2.5	0.4

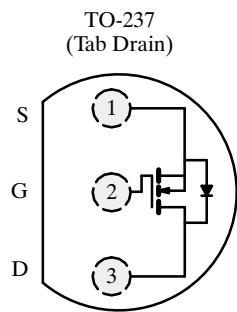
### Features

- Low On-Resistance:  $3.6 \Omega$
- Low Threshold: 1.6 V
- Low Input Capacitance: 35 pF
- Fast Switching Speed: 6 ns
- Low Input and Output Leakage



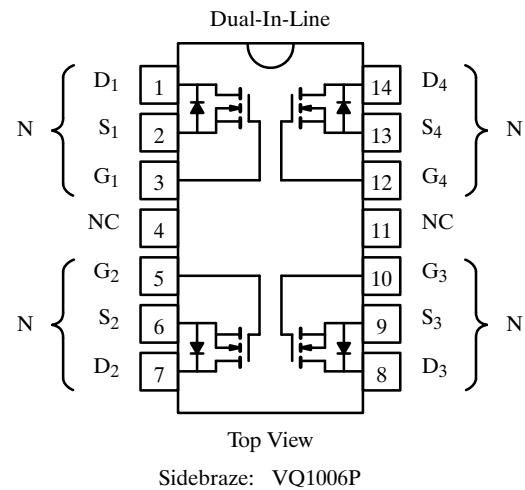
### Benefits

- Low Offset Voltage
- Low-Voltage Operation
- Easily Driven Without Buffer
- High-Speed Circuits
- Low Error Voltage



### Applications

- Direct Logic-Level Interface: TTL/CMOS
- Drivers: Relays, Solenoids, Lamps, Hammers, Displays, Memories, Transistors, etc.
- Battery Operated Systems
- Solid-State Relays



### Absolute Maximum Ratings ( $T_A = 25^\circ\text{C}$ Unless Otherwise Noted)

Parameter	Symbol	VN0808L	VN0808M	VQ1006P		Unit
				Single	Total Quad	
Drain-Source Voltage	$V_{DS}$	80	80	90		V
Gate-Source Voltage	$V_{GS}$	$\pm 30$	$\pm 30$	$\pm 20$		
Continuous Drain Current ( $T_J = 150^\circ\text{C}$ )	$I_D$	0.3	0.33	0.4		A
		0.19	0.21	0.23		
Pulsed Drain Current <sup>a</sup>	$I_{DM}$	1.9	1.9	2		
Power Dissipation	$P_D$	0.8	1	1.3	2	W
		0.32	0.4	0.52	0.8	
Maximum Junction-to-Ambient	$R_{thJA}$	156	125	96	62.5	°C/W
Operating Junction and Storage Temperature Range	$T_J, T_{stg}$	−55 to 150				°C

Notes

a. Pulse width limited by maximum junction temperature.

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## Specifications<sup>a</sup>

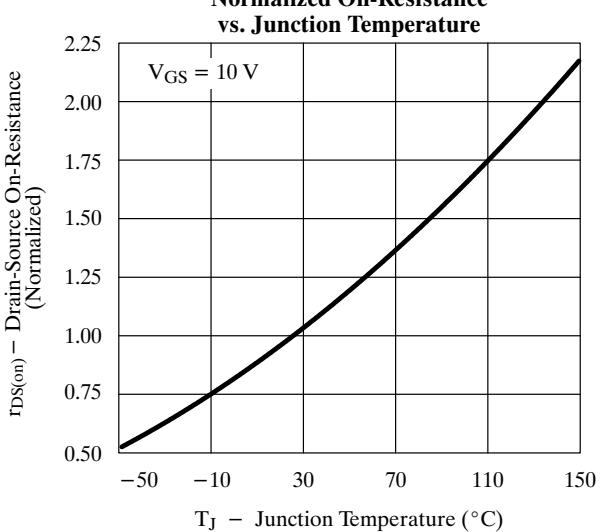
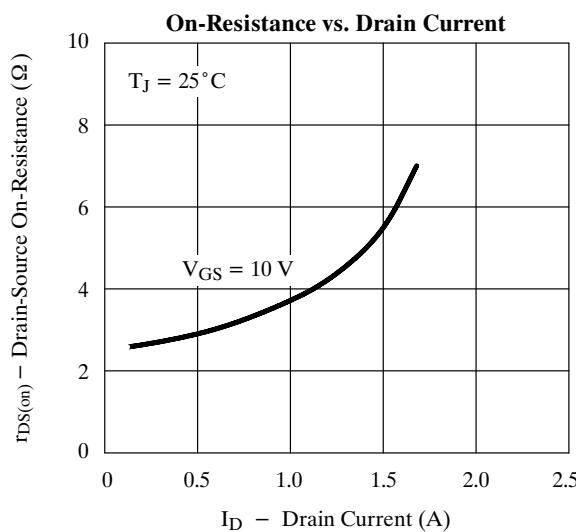
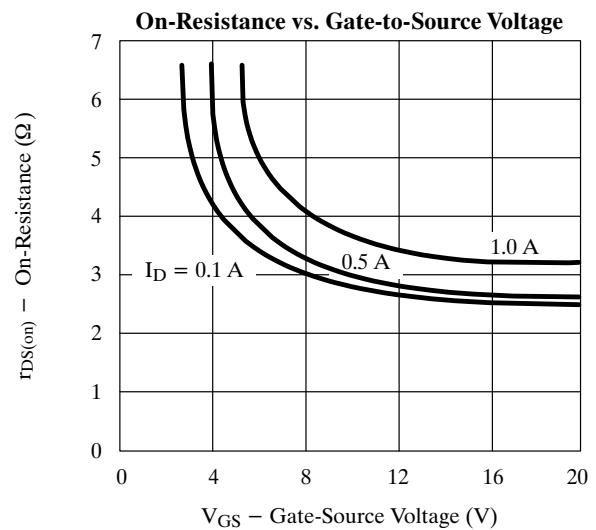
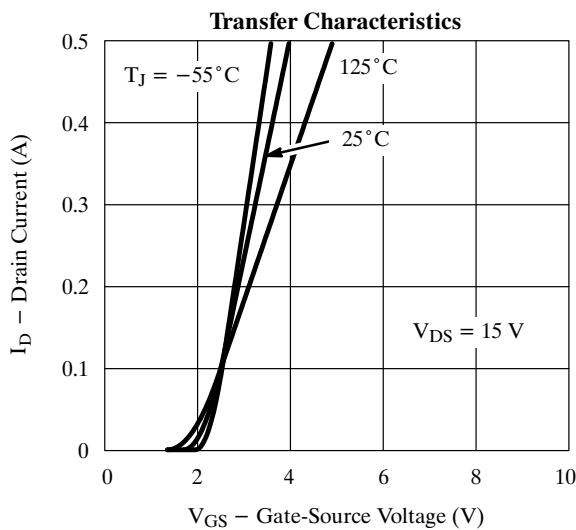
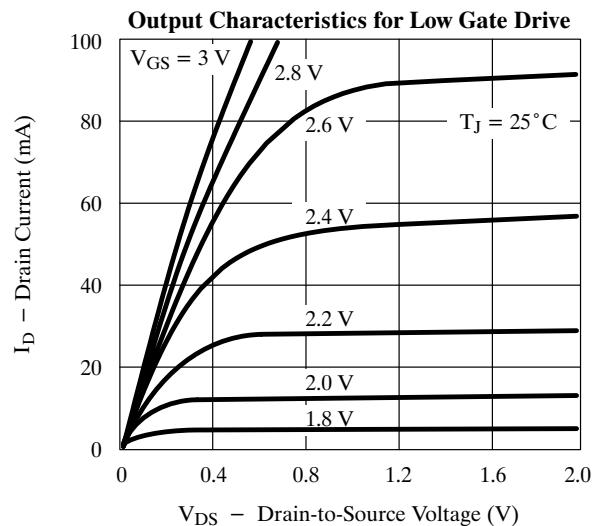
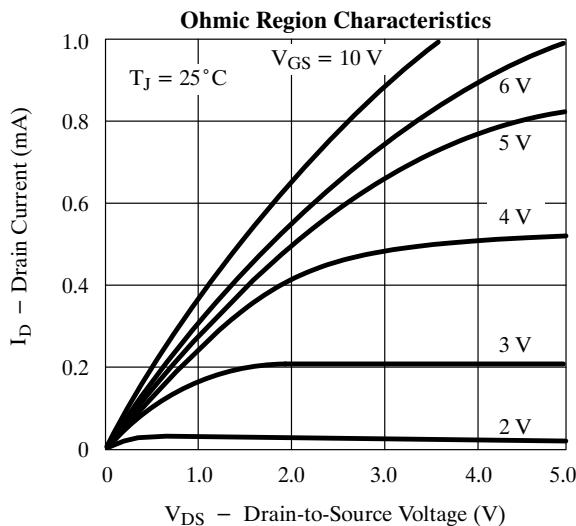
Parameter	Symbol	Test Conditions	Typ <sup>b</sup>	Limits				Unit	
				VN0808L/M		VQ1006P			
				Min	Max	Min	Max		
<b>Static</b>									
Drain-Source Breakdown Voltage	V <sub>(BR)DSS</sub>	V <sub>GS</sub> = 0 V, I <sub>D</sub> = 10 µA	125	80		90		V	
Gate-Threshold Voltage	V <sub>GS(th)</sub>	V <sub>DS</sub> = V <sub>GS</sub> , I <sub>D</sub> = 1 mA	1.6	0.8	2	0.8	2.5		
Gate-Body Leakage	I <sub>GSS</sub>	V <sub>DS</sub> = 0 V, V <sub>GS</sub> = ±15 V T <sub>J</sub> = 125°C			±100		±100	nA	
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	V <sub>DS</sub> = 80 V, V <sub>GS</sub> = 0 V T <sub>J</sub> = 125°C			10			µA	
		V <sub>DS</sub> = 72 V, V <sub>GS</sub> = 0 V T <sub>J</sub> = 125°C			500				
						1			
On-State Drain Current <sup>c</sup>	I <sub>D(on)</sub>	V <sub>DS</sub> = 10 V, V <sub>GS</sub> = 10 V	1.8	1.5		1.5		A	
Drain-Source On-Resistance <sup>c</sup>	r <sub>DS(on)</sub>	V <sub>GS</sub> = 5 V, I <sub>D</sub> = 0.3 A	3.8			5		Ω	
		V <sub>GS</sub> = 10 V, I <sub>D</sub> = 1 A T <sub>J</sub> = 125°C	3.6		4		4.5		
Forward Transconductance <sup>c</sup>	g <sub>fs</sub>	V <sub>DS</sub> = 10 V, I <sub>D</sub> = 0.5 A	350	170		170		mS	
Common Source Output Conductance <sup>c</sup>	g <sub>os</sub>	V <sub>DS</sub> = 10 V, I <sub>D</sub> = 0.1 A	0.23						
<b>Dynamic</b>									
Input Capacitance	C <sub>iss</sub>	V <sub>DS</sub> = 25 V, V <sub>GS</sub> = 0 V, f = 1 MHz	35		50		60	pF	
Output Capacitance	C <sub>oss</sub>		15		40		50		
Reverse Transfer Capacitance	C <sub>rss</sub>		2		10		10		
<b>Switching<sup>d</sup></b>									
Turn-On Time	t <sub>ON</sub>	V <sub>DD</sub> = 25 V, R <sub>L</sub> = 23 Ω I <sub>D</sub> ≈ 1 A, V <sub>GEN</sub> = 10 V R <sub>G</sub> = 25 Ω	6		10		10	ns	
Turn-Off Time	t <sub>OFF</sub>		8		10		10		

### Notes

- a. T<sub>A</sub> = 25°C unless otherwise noted.
- b. For DESIGN AID ONLY, not subject to production testing.
- c. Pulse test: PW ≤ 300 µs duty cycle ≤ 2%.
- d. Switching time is essentially independent of operating temperature.

VNDQ09

## Typical Characteristics (25°C Unless Otherwise Noted)



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## Typical Characteristics (25°C Unless Otherwise Noted) (Cont'd)

